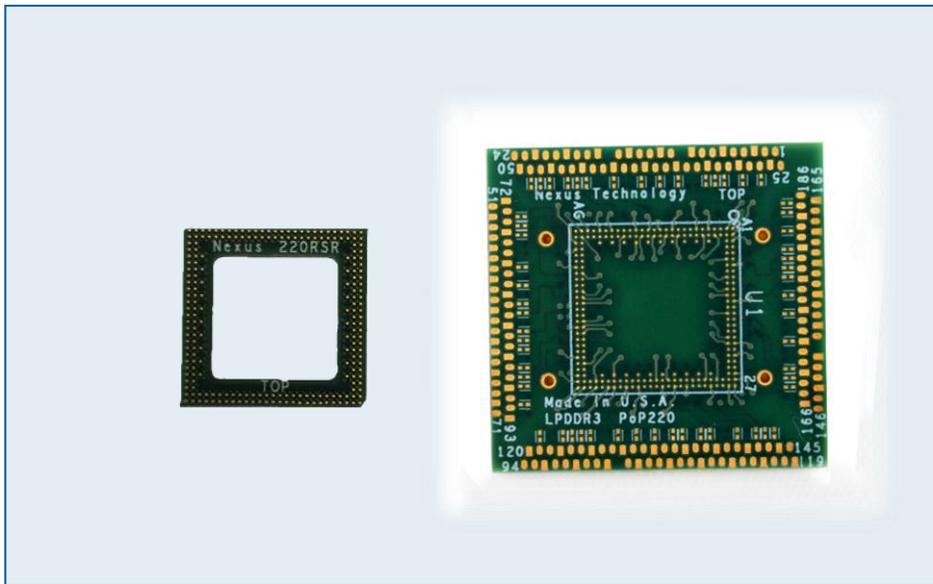




220 Ball LPDDR2/LPDDR3 PoP Oscilloscope Component Interposer

- Optimal Analog Validation
- Use with Existing Embedded / Mobile Designs
- Designed for speeds of:
 - LPDDR2-1067+
 - LPDDR3-1600+
- Scope Probe Tips Designed into the Interposer
- Socket Design – also available without a socket
- Support for LPDDR3 Memory Devices
 - Package on Package (PoP)
 - 14mm X 14mm
 - 2x32 Data Width
 - 0.5mm Pitch
- S Parameters available for Simulation



This Memory Component Interposer (MCI) BGA adapter has been designed to provide a high fidelity, easy to probe adapter that connects between your target Board and your memory component. Memory Component Interposers compliment the oscilloscope adapters providing a complete debug solution.

The Pop Challenge

Low Power DDR3 (LPDDR3) memory components are expanding rapidly in the market providing low power, high bandwidth, high density memory solutions. The Package on Package version results in target space saving but introduces significant roadblocks for test/debug and analysis of the memory interface.



Figure 3 - Side view (photo) of PoP memory soldered onto a processor

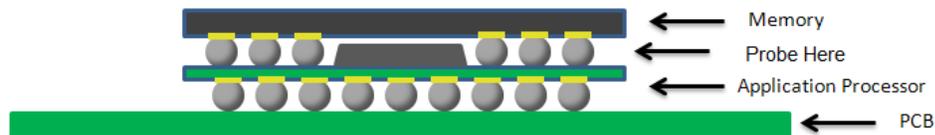


Figure 2 - Side view (Drawing) of the PoP memory soldered onto a processor

LPDDR2 / LPDDR3 Memory Socket Component Option

Interposers are available without the memory socket on them. If the product is ordered this way, it is the customer's responsibility to mount the memory IC onto the Interposer. Ordering with a memory socket allows for easy BGA memory component installation and removal for the quick swapping and testing of different memory components on the interposer.

The two types of Socketed Memory Components:

- NEX-LP2PoP220BSC – LPDDR2 PoP 220 ball MCI. No memory socket installed on MCI (solder balls only on bottom of interposer). Includes one riser. Note: riser ships without solderballs.
- NEX-LP2PoP220BSCSK – LPDDR2 PoP 220 ball with memory socket installed on MCI (solder balls only on bottom of interposer). Includes one riser. Riser ships without solderballs attached.
- NEX-LP3PoP220BSC – LPDDR3 PoP 220 ball MCI. No memory socket installed on MCI (solder balls only on bottom of interposer). Includes one riser. Note: riser ships without solderballs.
- NEX-LP3PoP220BSCSK – LPDDR3 PoP 220 ball with memory socket installed on MCI (solder balls only on bottom of interposer). Includes one riser. Riser ships without solderballs attached.

A socket on the interposer provides the ability to quickly and easily change memory components in a target. Simply remove and insert different memory components to validate multiple memory vendor's devices.

If purchased without a memory socket (NEX-LP2PoP220BSC or NEX-LP3PoP220BSC), memory will need to be soldered directly to interposer.

Memory Component Interposer Installation

Assemble the Memory Component Interposer onto the riser as shown in Figure 3 (Riser is optional). Care should be taken to ensure that the balls on the adapter align correctly with the riser on the target. Pin 1A needs to be matched to 1A on the user's board under test (Target).

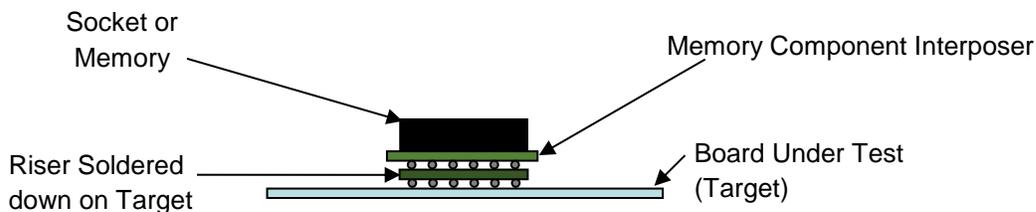


Figure 3 - Side view of the complete interposer installation

Oscilloscope Component Interposer Hardware

Connection to an oscilloscope is enabled by using oscilloscope memory component interposers. These controlled impedance; matched trace length interposers provide analog visibility using an oscilloscope. Signals are brought out to probe points that are designed to accommodate solder down probe tips. For more information, please see the [Nexus Soldering Guide](#). Removable oscilloscope probe tips can also be used to easily move the oscilloscope probe between signals for quick and accurate measurement.

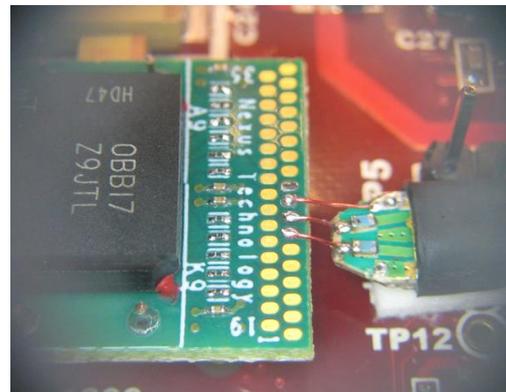


Figure 4 - Soldered down probe tips

Oscilloscope Analog Validation

Filter software available for your oscilloscope removes the effect of the oscilloscope interposer. Although these interposers are designed to optimize signal integrity, this feature removes even the slightest effect the adapter has from the oscilloscope display.

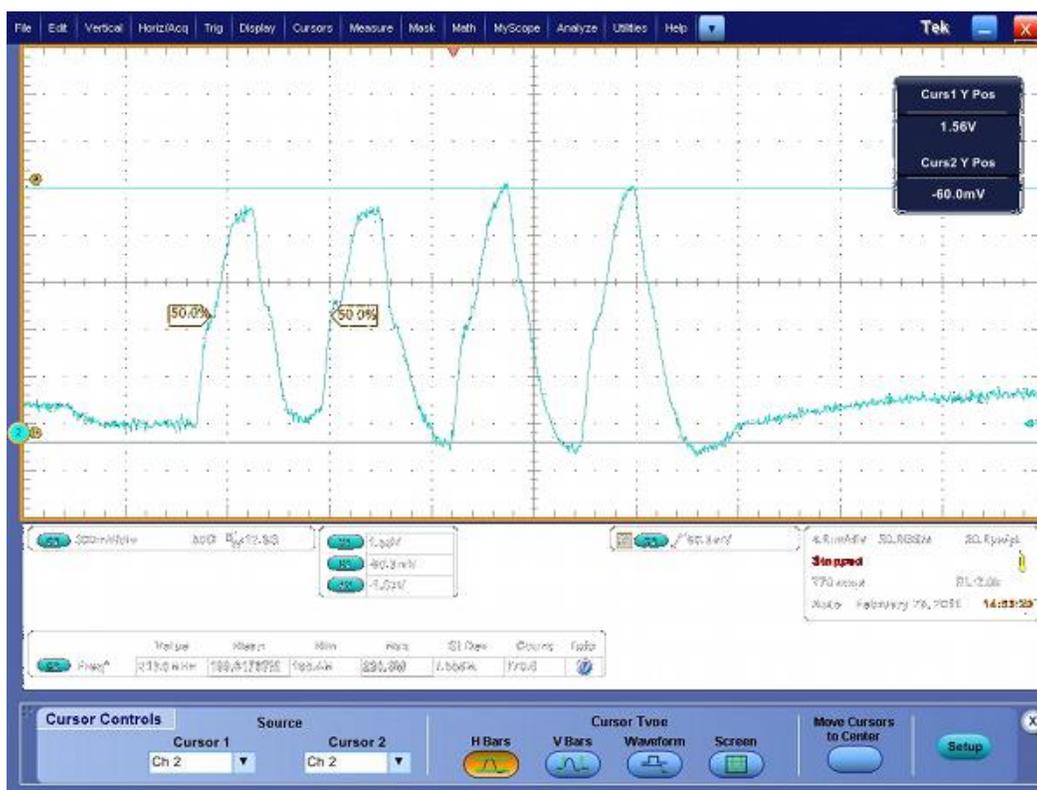


Figure 5: Strobe as seen using the Oscilloscope Component Interposer

Nexus Technology's Component Interposer Advantages

Probed at the BGA Pads

The best place to probe to eliminate reflections associated with standard embedded LPDDR3 mid bus probing or other methods is at the BGA pads. Interposers require no target footprints or special routing requirements that mid bus probing requires.

Use with Existing Embedded Designs

No need to change existing designs. Simply add the interposer to your embedded target with no re-design or added probe points.

Easy to Install

Just install the interposer and riser by using industry standard BGA attachment methods or by utilizing Nexus Technology's attachment service.

Oscilloscope Interposer software

Oscilloscope de-embedding filter software removes the effects of an interposer on the system. Please contact Nexus for more information.

Interposer Riser for the Target

An optional riser can be used to connect the SoC to the interposer. The mechanical dimensions for Riser is shown in Figure 6.

Product Dimensions

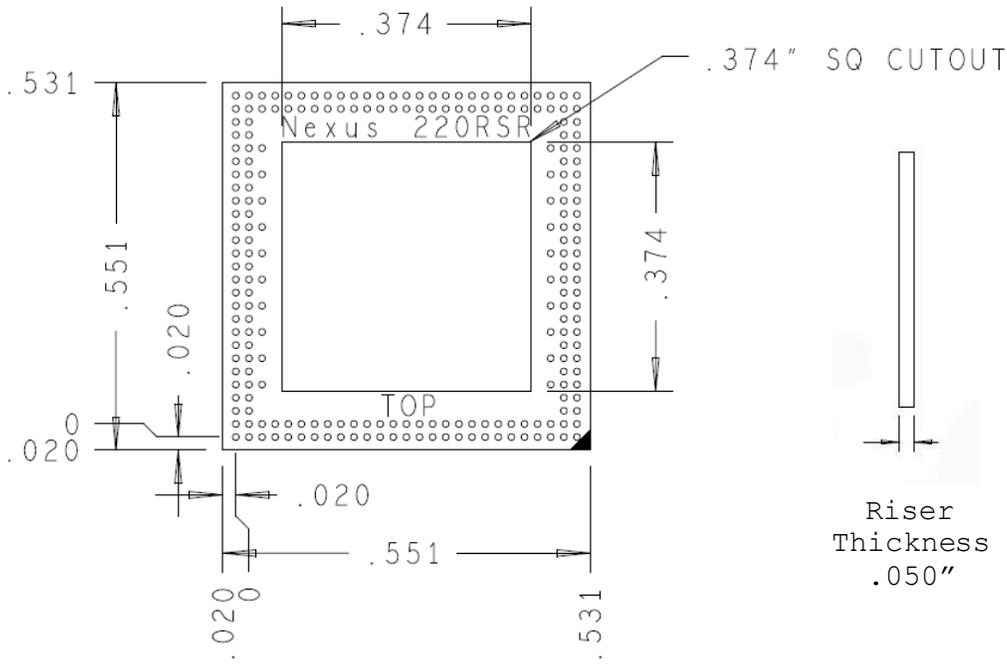


Figure 6: LPDDR2/LPDDR3-220 ball Riser Dimensions

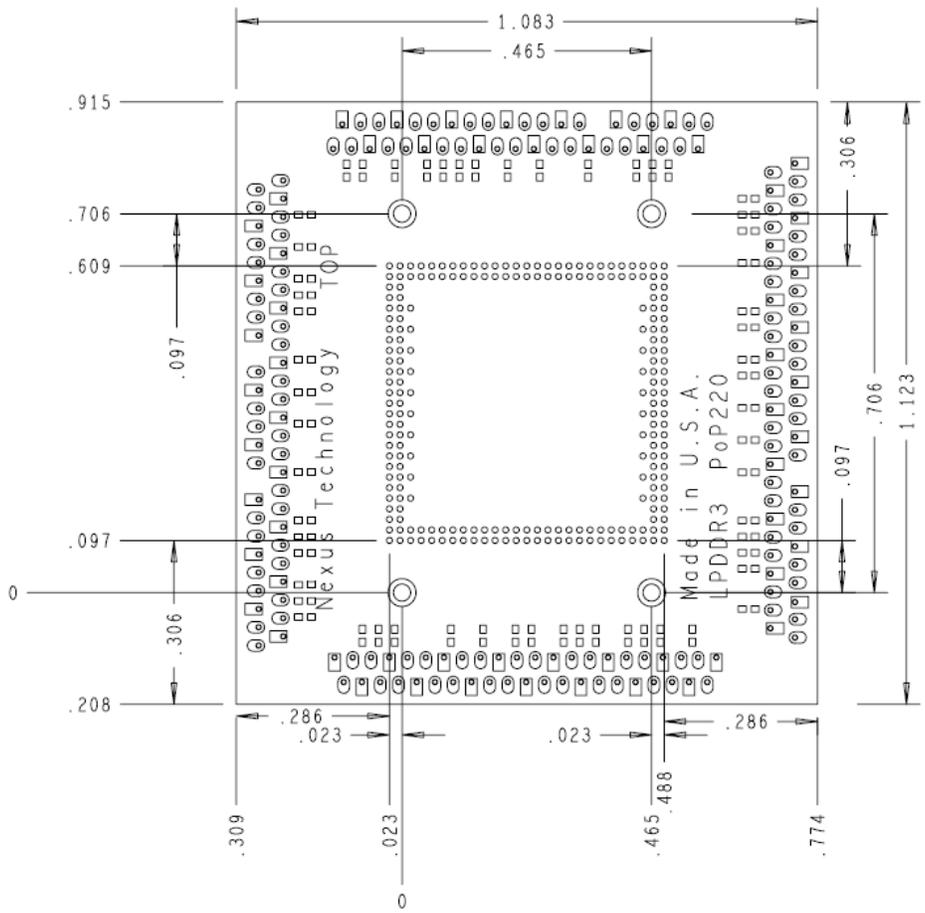


Figure 7: LPDDR2/LPDDR3 220-Ball PoP Oscilloscope Component Interposer Dimensions

Product Configuration Tables

LPDDR3 PoP 220-ball Oscilloscope Interposers

Nomenclature	Description	Interposer Type	Data Width	Memory Socket Included
NEX-LP2PoP220BSC	LPDDR2 PoP 220 ball MCI. No memory socket installed on MCI (solder balls only on bottom of interposer). Includes one riser. Note: Riser ships without solderballs.	Oscilloscope	2x32	No
NEX-LP2PoP220SCSK	LPDDR2 PoP 220 ball with memory socket installed on MCI (solder balls only on bottom of interposer). Includes one riser. Riser ships without solderballs attached.	Oscilloscope	2x32	Yes
NEX-LP3PoP220BSC	LPDDR3 PoP 220 ball MCI. No memory socket installed on MCI (solder balls only on bottom of interposer). Includes one riser. Note: Riser ships without solderballs.	Oscilloscope	2x32	No
NEX-LP3PoP220SCSK	LPDDR3 PoP 220 ball with memory socket installed on MCI (solder balls only on bottom of interposer). Includes one riser. Riser ships without solderballs attached.	Oscilloscope	2x32	Yes

Optional Add On Accessories

Nomenclature	Description	Solderballs Included
NEX-RSRLPDDR2220	Qty 1: LPDDR2 220 ball riser	No
NEX-RSRLPDDR3220	Qty 1: LPDDR3 220 ball riser	No
NEX-OPT-SOLDERBALLS-RSR	Qty 1: add solderballs to riser	Option
Attachment Service	Nexus provides an optional service for the removal of a memory component from the target under test and the re-balling of the removed memory component as well as the attachment of the riser and interposer onto the user supplied target under test. This attachment is similar to soldering a BGA component onto a Board.	

Further Information

Please contact us by telephone, email or mail as listed below. Normal business hours are 9:00 – 5:00 EST.

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The logo for Nexus Technology, featuring the word "NEXUS" in a bold, blue, sans-serif font with a small red triangle above the letter "U". Below "NEXUS" is the word "TECHNOLOGY" in a smaller, blue, sans-serif font.

